

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	418	257/791.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2011/05/27 14:12
L2	11439	438/124.ccls. 438/126.ccls. 438/127.ccls. 257/787.ccls. 257/788.ccls. 257/791.ccls. 257/e23.12.ccls. 257/ e21.504.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2011/05/27 14:27
L3	464	L2 and ((siloxane polysiloxane organosiloxane organopolysiloxane silicone) same (inject\$6 mold\$6 cavity) same (heat \$6 curable curing cure cured liquid))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2011/05/27 14:27
L4	140	(CHENG-TAMMY DOBRZELEWSKI DOBRZELEWSKI-M DOBRZELEWSKI-MARK SOLOMON-DANIEL SOLOMON-DANIEL-M SOLOMON-DANIEL-STEVEN SOLOMON-D WINDIATE-C WINDIATE-CHRISTOPHER WINDIATE).in.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2011/05/27 14:34
L5	8	L4 and (siloxane polysiloxane organosiloxane organopolysiloxane silicone)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2011/05/27 14:34
L6	289	((siloxane polysiloxane organosiloxane organopolysiloxane silicone) with (composition liquid encapsula\$6 resin epoxy)) and (inject\$6 with (mold\$6 cavity)) and (heat \$6 curable curing cure cured) and (clamp\$6 force ton pressure speed mpa pascal megapascal)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/27 14:35

L7	414	((siloxane polysiloxane organosiloxane organopolysiloxane silicone) with (composition liquid encapsula\$6 resin epoxy)) same (inject\$6 with (mold\$6 cavity)) same (heat\$6 curable curing cure cured) same (clamp\$6 force ton pressure speed mpa pascal megapascal)	US-PGPUB; USPAT	OR	ON	2011/05/27 14:38
L8	40	((siloxane polysiloxane organosiloxane organopolysiloxane silicone) with (composition liquid encapsula\$6 resin epoxy)) same (inject\$6 with (mold\$6 cavity)) same (heat\$6 curable curing cure cured) same (addition near2 reaction)	US-PGPUB; USPAT	OR	ON	2011/05/27 14:42
L9	37	((siloxane polysiloxane organosiloxane organopolysiloxane silicone) with (composition liquid encapsula\$6 resin epoxy)) same (inject\$6 with (mold\$6 cavity)) same (heat\$6 curable curing cure cured) same ((chip die component element ic integrated substrate dice) with (bond \$6 join\$6 attach\$6 mount \$6) with (siloxane polysiloxane organosiloxane organopolysiloxane silicone) with (composition adhe\$8))	US-PGPUB; USPAT	OR	ON	2011/05/27 14:43
L10	72	((siloxane polysiloxane organosiloxane organopolysiloxane silicone) with (composition liquid encapsula\$6 resin epoxy)) same (inject\$6 with (mold\$6 cavity) with gate) same (heat\$6 curable curing cure cured)	US-PGPUB; USPAT	OR	ON	2011/05/27 14:45

L11	40	(composition liquid encapsula\$ resin epoxy) same (inject\$ with (mold\$ cavity) with gate) same (heat\$ curable curing cure cured) same (bond\$ near wir\$)	US-PGPUB; USPAT	OR	ON	2011/05/27 14:45
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**EAST Search History (1 Interference)**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L12	60	(((((siloxane polysiloxane organosiloxane organopolysiloxane silicone) with (composition liquid encapsula\$ resin epoxy)) and (inject\$ with (mold\$ cavity)) and (heat\$ curable curing cure cured) and (clamp\$ force ton pressure speed mpa pascal megapascal) and (semiconductor silicon die dice ic integrated element chip wafer substrate packag\$)).clm.	US-PGPUB; UPAD	OR	ON	2011/05/27 14:50

5/ 27/ 11 2:55:51 PM

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